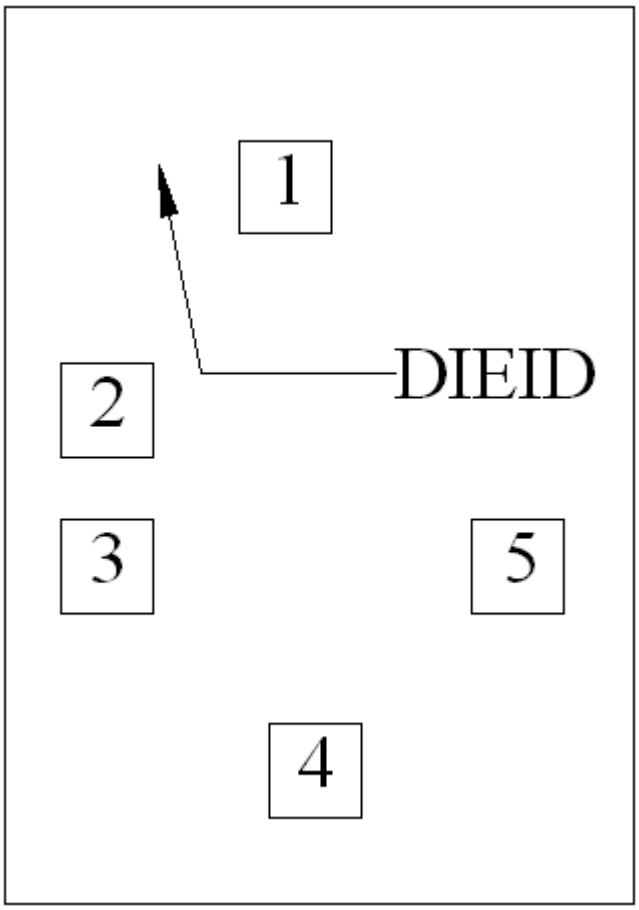
LMH6702 MDC MWC
ULTRA LOW DISTORTION, WIDEBAND OP AMP

May 10,2004

DIE LAYOUT (F-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LMH6702F	Bond Pad Opening Size (min)	92µm x 92µm
Die Step	F	Bond Pad Metalization	0.5%COPPER_BAL. ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	622µm x 889µm 24.5mils x 35.0mils	Back Side Connection	V-
Thickness	254µm Nominal		
Min Pitch	155µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (F -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
INPUT -	1	-33	266	92	x	92
INPUT+	2	-210	45	92	x	92
V -	3	-210	-110	92	x	92
OUTPUT	4	-4	-312	92	x	92
V+	5	197	-110	92	x	92

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IN U.S.A.
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Fax: 1 207 541 6140

IN EUROPE
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Fax: 49 (0) 8141 351470

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